

IN THE SPECIFICATION

**Page 1, before the first line, add the paragraph:**

This is a continuation application of U.S. Serial No. 10/108,439, filed March 29, 2002 (now allowed), which is a continuation application of U.S. Serial No. 10/108,483, filed March 29, 2002 (now U.S. Patent No. 6,590,276), which is a continuation application of U.S. Serial No. 09/733,929, filed December 12, 2000 (now U.S. Patent No. 6,399,423).

**Page 1, line 7, replace line with:**

~~BACKGROUND OF THE INVENTION~~ FIELD OF THE INVENTION

**Page 1, between lines 12 and 13, add the line:**

DESCRIPTION OF THE RELATED ART

IN THE ABSTRACT

~~To improve the connection reliability at the time of packaging a semiconductor device and to make the method management easy in a semiconductor device manufacturing method.~~

The semiconductor device comprises: a tube 1 for supporting a semiconductor chip 2; a sealing body 3 formed by sealing the semiconductor chip 2 with a resin; a plurality of leads made of a copper alloy, exposed to the back face 3a of

the sealing body 3, and having a soldered layer 8—on the exposed mounted face 1d; and wires 4—for connecting the pads 2a—of the semiconductor chip and the corresponding leads 1a. In the manufacture method, the sealing body 3—is polished, after resin-molded, at its back face 3a—with a brush to form the two widthwise edge portions, as exposed from the back face 3a—of the sealing body 3, of the lead 1a—into rounded faces, and the mounted face 1d—of the lead 1a—including the rounded faces is protruded at its central portion from the back face 3a—of the sealing body 3—thereby to improve the connection reliability at the packaging time.